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(58) Field of search

C3R

C3N

Selected US specifications from IPC sub-classes C08L C08G C09J

(54) A substitute for amino and phenolic resins

- (57) A substitute for amino and phenolic resins is used in the polycondensation of such resins based on formaldehyde for bonding water penetrable cellulosic particles. The substitute comprises an aqueous
- a) either at least one aldehyde together with at least one amide and/or together with at least one phenol, or a non-resinous condensation product of formaldehyde and urea, and
- b) a sugar or a sugar derivative or their by-products or a starch or its degradation products or a mixture thereof, and/or
 - c) a raw and/or treated lignosulfonate.

This substitute also reduces the free formaldehyde of the resulting board without impairing the other properties thereof.

SPECIFICATION

65 with the following limitations:

1

Substitute for amino and phenolic resins

5 The present invention relates to a substitute for amino and phenolic resins in the polycondensa-5 tion of such resins based on formaldehyde for bonding water penetrable cellulosic particles thus allowing lower amounts of resin solids to be used while at the same time reducing the free formaldehyde of the resulting board without imparting any loss in bonding strength, without requiring any extra steps in the production, without changing the curing rate of the production, 10 without causing any problem to the boilers when burning particleboard sander dust or edges 10 from cutting saws and without reducing the tack properties of the resin mixture. The said substitute is comprised mainly of a solution of: a) either an aldehyde together with an amide or together with a phenol, or a non-resinous condensation product of formaldehyde and urea, and 15 b) a sugar or a sugar derivative or their by-products or a starch or a mixture thereof, and/or 15 c) a raw and/or treated lignosulfonate or similar products. The aldehyde is preferably formaldehyde, for example in the form of paraformaldehyde, or acetaldehyde. The amide is preferably mainly urea or thiourea or their homologues or melamine, benzoguanamine or dicyandiamide or their homologues. The phenol is preferably phenol itself or 20 resorcinol. 20 Among the sugars, sugar derivatives, their by-products and mixtures thereof, molasses, dextrose, glucose, fructose or sucrose or mixtures thereof such as corn syrup are most preferred. Among the starches, wheat starch, modified starches, dextrin and the like are interesting. Examples of raw lignosulfonates are black liquor and similar products, and examples of treated 25 25 lignosulfonates are sodium, calcium and ammonium lignosulfonate. The substitute of the invention preferably contains 40 to 50% by weight of water. The weight of a) to b) and/or c) is preferably 0.1 to 50.0:1, most preferably 1.0 to 15.0:1. The combination of a) with b) and/or c) presents a synergistic behaviour. If the single components are added alone to the resin they do not give good boards, but if they are added in 30 combination, they exhibit an improvement in the board properties obtained. The substitute 30 according to the present invention (calculated as 100% solids) may substitute as much as 30% of the resin solids used. Said substitute is not added in quantities equal to the quantities substituted. It is added in quantities from 50 to 90% of the amount of resin substituted (calculations referred to by weight and referring to all products as 100% solids). The substrate according to the present invention may therefore, because of its synergistic 35 behaviour, substitute the resin in quantities from 110% up to 200% of its own weight. When added to lower amounts e.g. up to 15% there is a considerable increase in the properties of the end product. When added to higher levels, i.e. up to 30%, no difference is imparted to the properties of the end product but the free formaldehyde is considerably reduced and the amount 40 of resin saved is considerably increased. 40 Bonding is effected by curing the resin mixture at elevated tempertures and pressures according to the methods well known in the art. The substitute may be used in all types of products where amino and phenolic resins are used for bonding lignocellulosic products, whether these are wood particles for particleboard production using a flat press, or a calender or wood veneers 45 such as in plywood production. 45 It is very interesting to note that the product has also good tack. This property otherwise called "green strength" is desired in some types of particleboard plants, specially the plants with multi opening press and in plywood factories, specially those having a pre-press. The quality of boards produced was controlled weekly for a period of six months and no 50 reduction in the properties was observed. This proves that no polymer degradation occurs and 50 that the ageing properties of the boards are comparable to the ones normally produced. The substitute of the invention can be prepared by plain mixing of the components. In order to obtain an acceptable shelf-life of the substitute, a base is preferably added to adjust the pH to a value in the range of 6 to 14. Substitutes so far known in the art to substitute resin have not succeeded in substituting such 55 high levels of resin by using lower amounts of the substitute and reducing simultaneously the free formaldehyde of the boards, without imparting any loss in bonding strength, without requiring any extra steps in the production, without charging the curing rate of the production, without causing any problems to the boilers when burning particleboard sander dust or edges from 60 cutting saws and without reducing the tack of the resin mixture. 60 In particular, the known substituents are lignosulfonates, sodium chloride or mixtures of formaldehyde with urea and sodium chloride. It is well known that lignosulfonates may not be used for quantities higher than 10%; otherwise, board properties will be reduced.

It is also known that the addition of halide salt alone succeeds in substituting part of the resin

Press temperature 200°C Press time 9sec/mm Pressure 33kp/cm²

65

-High substitutions, higher than 6 to 8%, may not be obtained, otherwise the board properties will deteriorate. -Substitution is obtained in ratios 1:1, while in the case of the substitute according to the present invention it is 1.1 to 2.0:1. 5 -When particleboard sander dust or edges from cutting saws are burnt in boiliers, the latter are 5 plugged within a few hours. -Tack is reduced when sodium chloride is added to the resin mixtures. When mixtures of sodium chloride with urea and formaldehyde are used the following shortcomings are present: 10 -The presence of salt in the mixture causes severe problems in the boilers when sander dust or 10 cutting saw edges of boards are burnt. That is caused because the presence of salt reduces the melting point of the mixture and as a result a molten mass deposits in the boiler forming a glass like deposit which adheres on the boiler thus plugging it. The other shortcoming of this product is the fact that tack is severely reduced, thus making it 15 difficult to use in the plywood industry where there is a pre-press and in particleboard plants 15 where a multi opening press is present requiring green strength of the mat. The product according to the present invention overcomes all of the above shortcomings. The substitute according to the present invention provides yet another advantage. Apart from substituting up to 30% of the resin by adding only 50 to 90% of the resin solids substituted, 20 and reducing the free formaldehyde of boards, it reduces also the free formaldehyde in the 20 production hall where workers are exposed to formaldehyde fumes. The following Examples illustrate the invention and are not intended as limitations. Example 1 Three samples were prepared according to the following formulations: 25 25 Sample No. 2 3 1 parts by weight Formaldehyde 100% 185 133 30 Urea 100% 370 226 30 Molasses 100% 555 156 Water 445 445 445 1000 1000 1000 35 35 The above mentioned samples were prepared by plain mixing at room temperature until the solids were completely dissolved. The pH of the final products was adjusted to 7.5 to 8.0. Glue formulations were then prepared as follows: 40 Glue formulation No. 0 1 2 3 40 parts by weight Urea formaldehyde resin (65% solids) 108.9 81.7 81.7 81.7 Water 13.8 13.8 13.8 13.8 45 Sample 1 27.2 45 Sample 2 27.2 Sample 3 27.2 7.1 7.1 Ammonium chloride (20%) 7.1 7.1 50 No. 0: Glue formulation is the blank and does not include any of the above mentioned samples. 50 No. 1: Glue formulation includes sample 1, whereby only formaldehyde and urea are included. No. 2: Glue formulation includes sample 2 whereby only molasses are included. No. 3: Glue formulation includes sample 3 whereby all three ingredients are added, namely, formaldehyde, urea and molasses. Sample 3 represents the product according to the present 55 invention. 55 These glue formulations were used separately to spray a constant quantity of dried wood The sprayed wood chips were then formed into a mat having a normal thickness of 16mm. These mats were then introduced into a hot press and boards were pressed at the following 60 conditions: 60

Boards were then tested and the results are reported in the following table.

-	Glue formulation No. Density (kg/m³) Thickness (mm)	0 582 15.4	1 591 15.2	2 583 15.5	3 582 15.4		5
ь	Internal bond (kg/cm²) 2 hrs thickness swelling (%) 24 hrs thickness swelling (%) Free formaldehyde	7.1 11.1 20.3	6.5 11.3 22.5	5.0 17.5 30.3	7.2 12.1 22.3		5
10	(mg/100g dry board) Moisture content (%)	24.1 5.5	18.3 5.0	21.8 5.4	18.7 5.0		10
15	It can be noticed from the a formaldehyde of boards, only invention gives boards equivale	sample 3	3 includi	ng the c	omponents acco	ording to the present	15
13	Example 2 This example proves the sylutionates.	_				naldehyde, urea and ligno-	
20	For this purpose the following	ig samp	es were	: brebare	u.		20
	Sample No.	1	2	3			
	Formaldehyde (100%)	parts b 185	y weigh -	nt 133			
	Urea (100%)	370		266			
25	Calcium lignosulfonate (100%) Water	 445	555 445	156 445			25
		1000	1000	1000			
30	The above mentioned sample solids were completely dissolved Glue formulations were then	ed. The	pH of t	he final	in mixing at roo products was ac	m temperature until the dijusted to 7.5 to 8.0.	30
35	Giao ioiii.aiatioii iioi) 1 s by wei	2 ght	3			35
	Urea formaldehyde resin (65% solids) 108		_	81.7			
	, , , , , , , , , , , , , , , , , , , ,	.8 13.8	3 13.8	13.8			
40	Sample 1	- 27.2	27.2	_			40
40	Sample 2 Sample 3		21.2	27.2			70
	Ammonium chloride (20%) 7	.1 7.	7.1	7.1			
45	These formulations were us The sprayed wood chips whether the sprayed wood chips when the sprayed wood conditions:	nere ther	formed	into a	mat having a no	minal thickness of 16mm.	45
50	Press temperature 200°C Press time 9sec/mm Pressure 33kp/cm² Boards were then tested an	d the rea	culte are	reporte	d in the followin	og table:	50
		_	1	2	3	.g (ab.o.	
55	Glue formulation No. Density (kg/m³)	0 580	591	590	5 584		55
00	Thickness (mm)	15.5	15.2	15.0	15.1		
	Internal bond (kg/cm²)	7.0	6.3	5.4	6.9		
	2 hrs thickness swelling (%)	11.2 20.6	11.3 22.5	17.8 29.5	11.8 23.8		
60	24 hrs thickness swelling (%) Free formaldehyde	20.0	۷۷.5	23.0	20.0		60
	(mg/100g dry board)	23.9	19.8	18.5	17.8 4.8		
		L O	L (1	4 6	/ı U		
	Moisture content (%)	5.8	5.0	4.5	4.0		
65	It will be noticed from the a fonates, sample 2, have the v	bove m	entioned	figures	that boards pro	duced with plane lignosul- iree components according	65

to out present invention, sample 3, have the best results. Actually boards of sample 3 are equivalent to the blank, 0, which is the resin mixture without any substitute, while giving at the same time a reduction in the free formaldehyde of the boards.

5

In this example two samples are illustrated whereby the ratio of formaldehyde to urea is different from the one used in the previous examples. Also the weight ratio between components a) and b) is different from the one of examples 1 and 2.

The following samples were prepared:

10 S

10					10
	Sample No.	1	2		
	·	parts	by weight		
	Formaldehyde (100%)	133	133		
	Urea (100%)	177	177		
15	Molasses (100%)	156	-		15
	Dextrin glue (100%)	30	_		
	Calcium lignosulfonate (100%)		186		
	Water	504	504		
				-	
20		1000	1000		20

The above mentioned samples were prepared by plain mixing at room temperature until the solids were completely dissolved. The pH of the final products was adjusted to 7.5 to 8.0. Glue formations were then prepared as follows:

25

30

20

25

Glue formulation No.	0	1	2	
	parts b	y weigh	nt	
Urea formaldehyde resin				
(65% solids)	108.9	87.1	87.1	
Water	13.8	13.8	13.8	
Sample 1	_	21.8	_	
Sample 2	-		21.8	

30

These glue formations were used separately to spray a constant quantity of dried wood chips. The sprayed wood chips were then formed into a mat having a nominal thickness of 16mm. These mats were then introduced into a hot press and boards were pressed at the following conditions:

7.1

40 Press temperature 220°C

Ammonium chloride (20%)

40

35

Press time 9sec/mm

Pressure 33 kp/cm²

Boards were then tested and the results are reported in the following table:

7.1

7.1

45	Glue formulation No.	0	1	2
	Density (kg/m³)	573	595	587
	Thickness (mm)	15.1	15.4	15.2
	Internal bond (kg/cm²)	8.1	8.7	8.9
	2 hrs thickness swelling (%)	10.5	10.0	9.8
50	24 hrs thickness swelling (%)	19.9	19.3	18.7
	Free formaldehyde			
	(mg 100g dry board)	46.6	39.2	34.3
	Moisture content (%)	5.9	5.3	5.0

55 It can be noticed from the above mentioned table that samples 1 and 2 including the substitute according to the present invention give boards equivalent to the blank, sample 0, while giving a significant free formaldehyde reduction and resin saving.

Example 4

This is a laboratory test for plywood using a phenolic resin. 60 The following samples were prepared:

60

|--|

	Sample No.	1	2		
5	Phenol (100%) Formaldehyde (100%) Molasses (100%) Ammonium lignosulfonate	180 80 120	y weight 200 100 180		5
10	(100%) Water	200 420	520 —		10
	Total	1000	1000		
15		al produ	icts was	t room temperature until the solids were combrought to 10.0 by means of addition of sodium as follows:	15
20	Glue formulation No.	•	1 s by we 80	2 ight 80	20
20	Phenol formaldehyde glue (1009 Hardener (calcium carbonate: wheat flour – weight ratio 50:50	0) 60	60	60	20
25	Water Sample 1 Sample 2 Wheat flour	107 	90 30.77 – –	90 30.77 10	25
30	Total Viscosity (mPa.s)	267 120	' 260.7 00 1300	7 270.77 1100	30
	3 ply boards.			sed to spread both sides of the core veneer for where they were pressed under the following	
35	Press time 8 minutes Pressure 10kp/cm²				35
40	All boards gave very good tack They were then pressed in a			the following conditions:	40
	Press temperature 130°C Press time 3.5 minutes Pressure 12kp/cm²	6 . II			
45	These boards were tested as They were immersed for 24 hat 20°C for one hour and then the Results were as follows:	nours in	water a	t 60°C. After this they were introduced in water as carried out.	45
50	Glue formulation No. 0 Grading 10/10	1 10/10	2 10/10		50
55	another 30 minutes. Samples ar comes off and the core shows core after the top veneer was s When gluing is satisfactory, the	n water e then up. The craped he surfa	under pascraped grading off.	oressure for 30 minutes and then in vacuum for with a knife on the surface until the top veneer depends on the amount of fibers showing in the appears after scraping with the knife must still be pred with fibers grading in 10 (excellent). As	55
60	more clean spots appear and le	ss fiber	s, gradin	ered with fibers grading is 10 (excellent). As g is diminished. A grading of 8 is still satisfactories with only a few clean spots	60

Example 5

Two samples were prepared according to the following formulations:

appearing. Lower grading is unsatisfactory.

60 tory, ant it means that the surface is mainly covered with fibers with only a few clean spots

35

40

	Sample No.	1	2		
	·	parts	by we	ght	
	Formaldehyde (100%)	100	140		
5	Urea (100%)	140	190		5
	Melamine (100%)	100	110		_
	Molasses (100%)	_	110		
	Ammonium lignosulfonate (100%)	150	_		
	Water	510	450		
10					10
	Total	1000	1000		,,
15	•	H of the	final pr	y plain mixing at 25 to 30°C until the solids oducts was adjusted to 8.5 to 10.0.	15
	Glue formulation No. 0	1	2		
	· •	/ weight			
	Kauramin 535 (63% solids) 108		92		
20	Hardener (1) 14.8	14.8 1	4.8		20
	Formic acid (20%) 4	4	4		
	Paraffin emulsion 5.5	5.5	5.5		

30	(1) The Hardener solution was:	hot water urea ammonium chloride	462 384 154	3	30
		Total	1000		

35 These glue formulations were used separately to spray a constant quantity of dried wood chips with 12% dry glue/dry wood.

The sprayed wood chips were then formed into a mat having a normal thickness of 16mm. These mats were then introduced into a hot press and boards were pressed at the following conditions:

40

Press temperature 200°C Press time 10sec/mm

Pressure 35kp/cm²

Sample 1 Sample 2

25 Water

Boards were then tested and the results are reported in the following table.

16

13

13

16

13

45				
	Glue formulation No.	0	1	2
	Density (kg/m³	686	687	685
	Thickness (mm)	15.9	15.7	15.7
	Internal bond (kg/cm²)	6.6	6.5	6.4
50	2 hrs thickness swelling (%)	3.2	3.2	2.9
	24 hrs thickness swelling (%)	9.2	9.0	8.5
	V-100 (kg/cm²)	1.6	1.5	1.6

The V-100 test is carried out as follows:

The samples to be tested are placed in water at 20 ± 5°C. This water is warmed up in 1 to 2 hours to 100°C. The water temperature is kept at 100°C for 2 hours. It is important that there is a space of at least 15mm on all sides of every sample so as to make sure that water is freely introduced in the samples. The samples are then introduced for at least 1 hour in a refrigerator at 2 ± 5°C. Water is then allowed to drip and the wet samples are tested again for 60 internal bond.

Example 6

The following example will illustrate the fact that products according to our present invention may be produced by means of a variety of raw materials.

65 Samples were prepared according to the following formulations:

	Sample No.	1	2	. 3			
5	Paraformaldehyde Precondensate 80% (1) Acetaldehyde 100% Urea 100%	950 150		ght - - 130 200			5
10	Sucrose 100% Molasses 100% Ammonium lignosulfate 100% Dextrin 100% Water	50 50 - 400	40	- 210 - 460			10
15	(1) Precondensate containing 53 and 20 parts by weight of water The above mentioned samples dissolved. The pH of the final proprepared as follows:	were	prepare	d by pla	in mixing ur	itil the solids were completely	15
20	Glue formulation No. 0	1	2	3		•	20
25	Urea formaldehyde resin (65% solids) Water Sample 1 Sample 2 Sample 3 Ammonium chloride (20%)	93 13.8 15.9 - - 7.1	93	93 13.8 - - 15.9 7.1			25
30	These glue formulations were u	used s	eparate	ly to spi	ay a consta	nt quantity of dried of wood	30
	chips. The sprayed wood chips were These mats were then introduced conditions:						
35	Press temperature 200°C Press time 9sec/mm Pressure 33kp/cm²		ı.		i ta da centra	a den teleler	35
40	Boards were then tested and the			•		owing table:	40
		0 00 15.8	1 610 15.9	2 590 15.7	3 580 15.6		
45		6.8 10.5	6.9 10.3	7.1 10.1	6.5 9.9		45
	Free formaldehyde	20.1 22.3	19.5 18.0	19.9 16.2	20.3 17.1		
	Moisture content (%)	5.7	5.3	5.5	5.6		
50	Boards obtained with all glue form	mulatio	ns are	equivale	nt.		50

Example 7

In this example four samples were prepared according to the following formulations:

	Somnia Na	4		_			
	Sample No.	1	2	3	4		
	Formaldehyde	рагтs г 100	y weigh		400		
5	Resorcinol	100	100	100	100		
	Thiourea	50	50	_	-		5
	Urea	140	150	70	70		
	Benzoguanamine	-	150	80	70		
	Dicyandiamide		_	-	80		
10	Wheat starch		50	_	-		
	Dextrose	_	_		50		10
	Glucose	_	50	_	-		
	Fructose	-	_	50	_		
	Modified starch *	50	_	_			
15	Corn syrup	60	_	_	_		
	Molasses	_	_	50	100		15
	Black liquor	_	100	_	_		
	Sodium lignosulfonate	100	_	150	100		
	Water	500	500	500	500		
20							20
	Total	1000	1000	1000	1000		20
25	The above mentioned	sample	es were	prepare the fina	ed by p	molecular weight and, therefore, a low lain mixing at 40 to 50°C until the solids cts was adjusted to 8.5 to 10.0.	25
	Glue formulation No.	0	1	2	3	4	
30		Ŭ			y weigl	4	
	Urea formaldehyde resir	ו	•	pui to D	y weigi	n.	30
	(65%)	108.9	9 87.1	87.1	87.1	87.1	
	Water	13.8	8 13.8	13.8	13.8	13.8	
	Sample 1		21.8	_	_		
35	Sample 2	_	-	21.8		_	35
	Sample 3	-	_	_	21.8	_	35
	Sample 4		_	_	_	21.8	
	Ammonium chloride (20%	%) 7.1	7.1	7.1	7.1	7.1	
40	The sprayed wood ch	ips were	e then fo	ormed i	into a r	ray a constant quantity of dried wood nat having a nominal thickness of 16mm.	40
	conditions:	iiii ouuce	oom u	not p	ress an	d boards were pressed at the following	

conditions:

Press temperature 200°C Press time 9sec/mm

Pressure 33kp/cm²

45

Boards were then tested and the results are reported in the following table:

50 50 Glue formulation No. 0 1 2 3 4 Density (kg/m³) 625 617 633 631 628 Thickness (mm) 15.9 15.8 16.0 16.2 16.0 Internal bond (kg/cm²) 7.0 6.9 7.1 7.2 6.8 55 2 hrs thickn. swelling % 12.5 12.1 13.6 13.1 12.6 55 24 hrs thickn. swelling % 22.5 20.7 24.7 24.0 20.9 Free formaldehyde 2 (mg/100g dry board) 28.8 22.5 21.7 23.0 21.9 Moisture content % 6.1 5.7 5.9 5.9 6.2 60 60

It can be noticed from the above mentioned table that samples 1 to 4 including the substitute according to the present invention give boards equivalent to the blank, sample 0, while giving a significant free formaldehyde reduction and resin saving.

Three samples were prepared according to the following formulations:

	Three samples were prepared according to the following formulations.												
	Sample No.	1	2		3								
5	Formaldehyde 100% Urea 100% Sucrose 100%	135 365 10	by wei 135 365 -	135 365 –			5						
10	Molasses 100% Calcium lignosulfonate (100%) Water	- 490	10 490	10 490			10						
	Total	1000	1000	1000									
15	The above mentioned samples were prepared by plain mixing at 25 to 30°C until the solids were completely dissolved. The pH of the final products was adjusted to 8.5 to 10.0. Glue formulations were then prepared as follows:												
	Glue formulation No. 0	1	. 2	3		•							
20	Urea formaldehyde 108.5 resin (65% solids)	by weig 9 95.9	95.9	95.9			20						
25	Water 13.8 Sample 1 - Sample 2 - Sample 3 - Ammonium chloride 7. (20% solution in water)	13 _ _	13	13.8 - 13 7.1			25						
30	These glue formulations were used separately to spray a constant quantity of dried wood chips. The sprayed wood chips were then formed into a mat having a nominal thickness of 16mm. These mats were then introduced into a hot press and boards were pressed at the following conditions:												
35	Press temperature 200°C Press time 8sec/mm Pressure 35kp/cm² Boards were then tested and	the res	ults are	report	ed in the	e following table:	35						
40	Glue formulation No. Density (kg/m³) 5 Thickness (mm) Internal Bond (kg/cm²)	0 75 ! 15.4 8.3	1 582 15.3 8.7	2 579 15.5 8.9	3 6601 15.4 9.5		40						
45	2 hrs thickness swelling (%)	10.3 20.2 60.5	10.8 21.3 39.8	10.6 20.9 41.3	11.1 21.9 38.1	-	45						
	Moisture content (%)	6.0	7.1	6.8	6.5								

Boards obtained with all glue formulations are equivalent. Those however that include the substitute according to the present invention have lower free formaldehyde.

Example 9

Three examples were prepared according to the following formulations:

	Sample No.	1	. 2	3				
	Formaldehyde 100%	parts 85	s by we 85	ight 85				
5		-00	400	400		5		
	Sucrose 100%	32.3	_					
	Molasses 100% Calcium lignosulfonate (100%)	_	32.3	- 32.	3			
		82.7	482.7					
10						10		
	Total 1	000	1000	1000				
15		oH of	the fina	ıl produ	lain mixing at 25 to 30°C until the solids cts was adjusted to 8.5 to 10.0.	15		
	Glue formulation No. 0	1	2	3				
			veight	04.7				
20	Urea formaldehyde 108.9 resin (65% solids)	81.	7 81.7	81.7		20		
20	Water 13.8	13.8	3.8	13.8		20		
	Sample 1 -	27.2						
	Sample 2 – Sample 3 –	_	27.2	27.2				
25	Ammonium chloride 7.1	7.		7.1		25		
	(20% solution in water)							
	These alue formulations were a	ised (senarate	ly to s	pray a constant quantity of dried wood			
	chips.		sopulate	iy to si	or a constant quartity of affect wood			
30						30		
	conditions:	into	a not p	ress ar	d boards were pressed at the following			
25	Press temperature 200°C					25		
35	Press time 8sec/mm Pressure 35kp/cm ²					35		
	Boards were then tested and t	he res	sults are	report	ed in the following table:			
	Glue formulation No.	0	1	2	3			
40	Density (kg/m³) 61		-	597		40		
	Thickness (mm) 1	5.9	15.7	15.6	15.9			
		7.9	8.1	8.3	8.4			
	9 , ,	9.8 0.1	10.2 21.3	10.5 20.9	10.9 21.8			
45	Free formaldehyde 4	0.1	15.3	17.1		45		
	(mg/100g dry board)	7.0	7 1	76	9.0			
	Moisture content (%)	7.9	7.1	7.6	8.0			
Boards obtained with all glue formulations are equivalent. Those however that include the								
50	•	nt inv	ention h	nave a	very big formaldehyde reduction and resin	50		
	cost saving.							
	CLAIMS							
F- F-					ne polycondensation of such resins based	55 55		
55	on formaldehyde for bonding water penetrable cellulosic particles, characterized in that it com- prises an aqueous solution of							
	a) either at least one aldehyde together with at least one amide and/or together with at least							
	one phenol, or a non-resinous co	ndens	sation pi	roduct	of formaldehyde and urea, and			
60	b) a sugar or a sugar derivative a mixture thereof, and/or	or the	neır by-p	product	s or a starch or its degradation products or	60		
50	c) a raw and/or treated lignosu					55		
	2. A substitute according to o			cterized	I in that it contains 40 to 52% by weight			
	of water.							

3. A substitute according to claim 1 or 2, characterized in that the weight ratio of a) to b) 65 and/or c) is 0.1 to 50.0:1.

4. A substitute according to claim 3, characterized in that the weight ratio of a) to b) and/or c) is 1.0 to 15.0:1. 5. A substitute according to one of claims 1 to 4, characterized in that the aldehyde is formaldehyde or acetaldehyde. 6. A substitute according to one of claims 1 to 5, characterized in that the amide is urea, 5 thiourea, melamine, benzoguanamine or dicyandiamide. 7. A substitute according to one of claims 1 to 5, characterized in that the phenol is phenol itself or resorcinol. 8. A substitute according to one of claims 1 to 7, characterized in that component b) is 10 molasses, dextrose, glucose, fructose, sucrose, corn syrup, wheat starch, modified starch or 10 dextrin glue. 9. A substitute according to one of claims 1 to 8, characterized in that component c) is ammonium, sodium or calcium lignosulfonate or black liquor. 10. A process for preparing a substitute for amino and phenolic resins, characterized by 15 dissolving in water 15 a) either at least one aldehyde together with at least one amide and/or together with at least one phenol, or a non-resinous condensation product of formaldehyde and urea, and b) a sugar or a sugar derivative or their by-products or a starch or its degradation products or a mixture thereof, and/or 20 c) a raw and/or treated lignosulfonate. 20 11. A process according to claim 10, characterized by preparing a solution which contains 40 to 52% by weight of water. 12. A process according to claim 10 or 11, characterized in that the weight ratio of a) to b) and/or c) is 0.1 to 50.0:1. 13. A process according to claim 12, characterized in that the weight ratio of a) to b) and/or 25 c) is 1.0 to 15.0:1. 14. A process according to one of claims 10 to 13 characterized in that the aldehyde used is formaldehyde or acetaldehyde. 15. A process according to one of claims 10 to 14, characterized in that the amide used is 30 urea, thiourea, melaminde, benzoguanamine or dicyandiamide. 30 16. A process according to one of claims 10 to 14, characterized in that the phenol itself or resorcinol. 17. A process according to one of claims 10 to 16, characterized in that the component b) used as molasses, dextrose, glucose, fructose, sucrose, corn syrup, wheat starch, modified 35 starch or dextrin glue. 35 18. A process according to one of claims 10 to 17, characterized in that the component c) used is ammonium, sodium or calcium lignosulfonate or black liquor.

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